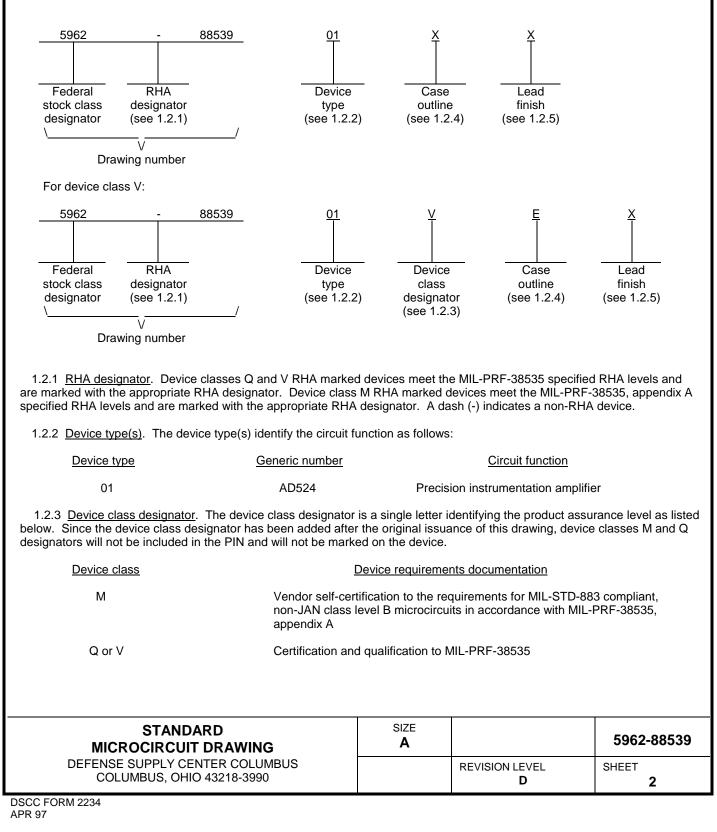
								ONS										
LTR				DESCR	IPTIO	N						DATE (YR-MO-DA)		APPROVED				
A	Add case outline throughout.	2. Add inp	out volta	ige test.	Add f	ootnote	e <u>3</u> /. Ed	litorial c	hanges	6		90-03-30		M. Poelking				
В	Change boilerpla	te to add o	one-par	t part nu	umbers	s. Add	table II	B for de	elta limi	itsrrp		97	-12-08			R. M	onnin	
С	Add radiation ha	dened ass	surance	require	ments	s Igt						99	-03-01		R. Monnin			
D	Replaced referent updated to reflect	ce to MIL-	STD-97	73 with r	referer	nce to I	MIL-PR	F-3853	5. Drav	ving		04	-08-06			R. M	onnin	
THE ORIGI REV SHEET REV SHEET REV STATUS	NAL FIRST SHEE	T OF TH		AWING	B HAS	BEEI	N REP	D	D. D	D	D	D	D	D	D	D	D	D
REV SHEET REV SHEET	S	REV SHE	ET PARED		D 1				D 5	6	7	8	9	D 10	11	12	13	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A	S	REV SHE PRE JOS	ET PARED SEPH A	BY KERB	D 1 Y	D	D	D	D 5	6 EFEN	7 SE SI DLUM	8 JPPL BUS,	9 Y CE	10	11 COL 218-39	12 UMB	13	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A ST/ MICR DR THIS DRAW FOR		REV SHE PRE JOS CHE CHJ	CKED E ARLES	BY KERBY BY E. BESC	D 1 Y ORE	D	D	D 4 MIC HAF	D 5 DE ROC	6 EFEN: CC	7 SE SI DLUM http	8 JPPL BUS, o://ww	9 Y CE , OHIC w.ds	10 NTER D 432	COL 218-39 a.mil TION	12 UMB 990	13 US	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A ST/ MICR DF THIS DRAW FOR DEP AND AGE	ANDARD S COCIRCUIT RAWING VING IS AVAILABLE USE BY ALL	REV SHE PRE JOS CHE CH, APP MO	CKED E ARLES	BY KERBY E. BESC	D 1 Y ORE KING	D 2	D	D 4 MIC HAF	D 5 DE ROC	6 EFEN: CC	7 SE SI DLUM http	8 JPPL BUS, o://ww	9 Y CE , OHIC w.ds	10 NTER D 432 cc.dla ADIA ISTR	COL 218-39 a.mil TION	12 UMB 990	13 US	
REV SHEET REV SHEET REV STATUS OF SHEETS PMIC N/A ST/ MICR DF THIS DRAW FOR DEP AND AGI DEPARTMI	ANDARD S COIRCUIT RAWING /ING IS AVAILABLE USE BY ALL 'ARTMENTS ENCIES OF THE	REV SHE PRE JOS CHE CH, MO DRA	CKED E ARLES	BY BY E. BESC DBY . POELK APPROV 88-02	D 1 Y ORE KING	D 2	D	D 4 MIC HAF		6 EFEN CC SIRCU JED, ER, N CA	7 SE SI DLUM http	BUS, BUS, S://ww LINE/ CISIC	9 Y CE , OHIC w.ds	10 NTER D 432 cc.dla ADIA ISTRI SILICO	11 218-39 a.mil TION UMEI ON	12 UMB 990		D 14

1. SCOPE

1.1 <u>Scope</u>. This drawing documents two product assurance class levels consisting of high reliability (device classes Q and M) and space application (device class V). A choice of case outlines and lead finishes are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of Radiation Hardness Assurance (RHA) levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following examples.

For device classes M and Q:



1.2.4 Case outline(s).	The case outline(s) are as des	signated in MIL-ST	D-1835 and as follows:	
Outline letter	Descriptive designator	Terminals	Package style	
E 2	GDIP1-T16 or CDIP2-T16 CQCC1-N20	16 20	Dual-in-line Square leadless chij	o carrier
1.2.5 <u>Lead finish</u> . The appendix A for device clas		IIL-PRF-38535 for	device classes Q and V or MIL-I	PRF-38535,
1.3 Absolute maximum	<u>ratings</u> . <u>1</u> /			
	tion (P _D)			
	·····			
	range (Т _{sтс}) Idering, 10 seconds)			
Thermal resistance				
Junction-to-case (0	лс)		See MIL-STD-1835	
Junction-to-ambient				
Case outline 2.			150° C/W	
1.4 <u>Recommended ope</u>	erating conditions.			
Supply voltage (V _S)			± 6 V dc to ± 18 V dc	
Ambient operating ter	nperature (T _A)		55°C to +125°C	
1.5 Radiation features.				
Maximum total dose a	available (dose rate = 50 – 300) rads(Si)/s)	100 Krads(Si)	
2. APPLICABLE DOCU	IMENTS			
2.1 <u>Government specifi</u> part of this drawing to the the solicitation or contract	extent specified herein. Unles	<u>ooks</u> . The followin ss otherwise specit	g specification, standards, and l fied, the issues of these docume	handbooks form a ents are those cited in
DEPARTMENT OF D	EFENSE SPECIFICATION			
MIL-PRF-38535 -	Integrated Circuits, Manufact	uring, General Spe	ecification for.	
	solute maximum rating may c degrade performance and affe		amage to the device. Extended	operation at the
	ucted only when specified in the		or contract.	
_				
		SIZE	:	
	ANDARD	A		5962-88539
	LY CENTER COLUMBUS			
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DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits. MIL-STD-1835 - Interface Standard Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings. MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <u>http://assist.daps.dla.mil/quicksearch/</u> or <u>www.dodssp.daps.mil/</u> or from the Standardization Document Order Desk, 700 Robbins Avenue, Building 4D, Philadelphia, PA 19111-5094.)

2.2 <u>Order of precedence</u>. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

3. REQUIREMENTS

3.1 <u>Item requirements</u>. The individual item requirements for device classes Q and V shall be in accordance with MIL-PRF-38535 and as specified herein or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. The individual item requirements for device class M shall be in accordance with MIL-PRF-38535, appendix A for non-JAN class level B devices and as specified herein.

3.2 <u>Design, construction, and physical dimensions</u>. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38535 and herein for device classes Q and V or MIL-PRF-38535, appendix A and herein for device class M.

3.2.1 <u>Case outline(s)</u>. The case outline(s) shall be in accordance with 1.2.4 herein.

3.2.2 <u>Terminal connections</u>. The terminal connections shall be as specified on figure 1.

3.2.3 Block diagram. The block diagram shall be as specified on figure 2.

3.2.4 Radiation exposure circuit. The radiation exposure circuit shall be as specified on figure 3.

3.3 <u>Electrical performance characteristics and postirradiation parameter limits</u>. Unless otherwise specified herein, the electrical performance characteristics and postirradiation parameter limits are as specified in table I and shall apply over the full ambient operating temperature range.

3.4 <u>Electrical test requirements</u>. The electrical test requirements shall be the subgroups specified in table IIA. The electrical tests for each subgroup are defined in table I.

3.5 <u>Marking</u>. The part shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's PIN may also be marked. For packages where marking of the entire SMD PIN number is not feasible due to space limitations, the manufacturer has the option of not marking the "5962-" on the device. For RHA product using this option, the RHA designator shall still be marked. Marking for device classes Q and V shall be in accordance with MIL-PRF-38535. Marking for device class M shall be in accordance with MIL-PRF-38535, appendix A.

3.5.1 <u>Certification/compliance mark</u>. The certification mark for device classes Q and V shall be a "QML" or "Q" as required in MIL-PRF-38535. The compliance mark for device class M shall be a "C" as required in MIL-PRF-38535, appendix A.

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	T	ABLE I. Electrica	l performanc	e characte	ristics.			
Test	Symbol	$\begin{array}{l} \text{Condition}\\ -55^\circ\text{C} \leq \text{T}_{\text{A}} \leq \\ \text{unless othe}\\ \text{specified} \end{array}$	+125°C erwise	Group A subgroup		Lim		Unit
						Min	Max	
Gain error 1	GE₁	$G = 1, V_0 = \pm 10$		1	01		±.05	%
		M,	D, P, L, R				.05	
Gain error 10	GE ₁₀	$G = 10, V_0 = \pm 1$	0 V	1	01		±.25	%
		М,	D, P, L, R				.25	
Gain error 100	GE100	G = 100, V ₀ = ±	-10 V	1	01		±.5	%
		M,	D, P, L, R				.5	
Gain error 1000	GE1000	G = 1000, V _O =	±10 V	1	01		±2.0	%
		М,	D, P, L, R				2.0	
Gain error drift 1	TCGE1	G = 1, V _O = ±10) V <u>2</u> /	2, 3	01		±5	ppm/°C
Gain error drift 10	TCGE ₁₀	G = 10, V _O = ±1	0 V <u>2</u> /	2, 3	01		±10	ppm/°C
Gain error drift 100	TCGE ₁₀₀	G = 100, V _O = ±	10 V <u>2</u> /	2, 3	01		±25	ppm/°C
Gain error drift 1000	TCGE ₁₀₀₀	G = 1000, V _O =	±10 V <u>2</u> /	2, 3	01		±50	ppm/°C
Input offset voltage	V _{OSI}	$V_{IN} = 0 V, T_A = 2$	25°C	1	01		±100	μV
		Μ,	D, P, L, R				1.0	mV
Input offset voltage drift	TCV _{OSI}	$V_{IN} = 0 V, G = 1$	000 <u>2</u> /	2, 3	01		±2	μV/°C
Output offset voltage	V _{oso}	$V_{IN} = 0 V, T_A = 2$	25°C	1	01		±3	mV
		М,	D, P, L, R				25	
Output offset voltage drift	TCV _{OSO}	$V_{IN} = 0 V, G = 1$	<u>2</u> /	2, 3	01		±50	μV/°C
Input bias current	Ι _Β	G = 1		1	01	-50	50	nA
				2, 3		-70	70	
		М,	D, P, L, R	1			1000	
Input offset current	I _{IO}	I _{IO} = (I _{B+}) - (I _{B-}) G = 1		1	01	-35	35	nA
		0-1		2, 3		-50	50	
		М,	D, P, L, R	1			100	
See footnotes at end of table.								
STA MICROCIRO		VING		SIZE A			5962	2-88539
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	IABLE	I. Electrical	performance ch	aracteristics - C	ontinued.			
Test	Symbol	-55°C ≤	ditions $\underline{1}/$ T _A \leq +125°C erwise specified	Group A subgroups	Device type	Lim	iits	Unit
						Min	Max	
Common mode rejection	CMRR1	G = 1 $V_{IN} = 0 V to$	<u>2</u> / o +10 V	1, 2, 3	01	70		dB
Common mode rejection	-CMRR1	G = 1 V _{IN} = 0 V to	<u>2</u> ∕ ⊳ -10 V	1, 2, 3	01	70		dB
Common mode rejection	CMRR10	G = 10 V _{IN} = 0 V to	<u>2</u> / 0 +10 V	1, 2, 3	01	90		dB
Common mode rejection	-CMRR10	G = 10 V _{IN} = 0 V to	o -10 V <u>2</u> /	1, 2, 3	01	90		dB
Common mode rejection	CMRR100	G = 100 V _{IN} = 0 V to	<u>2</u> / 0 +10 V	1, 2, 3	01	100		dB
Common mode rejection	-CMRR100	G = 100 V _{IN} = 0 V to	≥-10 V	1, 2, 3	01	100		dB
Common mode rejection	CMRR1000	G = 1000 V _{IN} = 0 V to	0 +10 V	1, 2, 3	01	110		dB
Common mode rejection	-CMRR1000	G = 1000 V _{IN} = 0 V to	o -10 V <u>2</u> /	1, 2, 3	01	110		dB
Power supply current	Icc	G = 1		1, 2, 3	01		5	mA
			M, D, P, L, R	1			5	
Power supply rejection	PSRR1	G = 1	<u>2/3/</u>	1, 2, 3	01	75		dB
Power supply rejection	PSRR10	G = 10	<u>2/ 3/</u>	1, 2, 3	01	95		dB
Power supply rejection	PSRR100	G = 100	<u>2/ 3</u> /	1, 2, 3	01	105		dB
Power supply rejection	PSRR1000	G = 1000	<u>2/ 3</u> /	1, 2, 3	01	115		dB

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	TABLE	I. Electrical performance cha	racteristics - Co	ontinued.			
Test	Symbol	$\begin{array}{c} Conditions \ \underline{1}/\\ -55^{\circ}C \leq T_A \leq +125^{\circ}C\\ \text{unless otherwise specified} \end{array}$	Group A subgroups	Device type	Lim	its	Unit
					Min	Max	
Input voltage	V _{IN}	Differential, linear, $\underline{2}/$ G = 1, T _A = 25°C	1	01	±10		V
		Common mode, linear $\underline{2}/$ G = 1, T _A = 25°C			± 7		
		Differential, safe, $T_A = 25^{\circ}C \underline{2}/ \underline{4}/ \underline{5}/$				± 36	
		Common, safe, T _A = 25°C <u>2/ 4/ 5</u> /				± 36	

<u>1</u>/ Devices supplied to this drawing have been characterized through all levels M, D, P, L, R of irradiation. However, this device is only tested at the "R" level. Pre and Post irradiation values are identical unless otherwise specified in table I. V_S = ±15 V, RL = 2 kΩ, unless otherwise specified.

2/ This parameter not tested post radiation.

 $\underline{3}$ / Power supply voltage tested at ±15 V with a swing to ±12 V.

4/ Input voltage (differential, safe) is the maximum voltage difference that can exist between the two input pins without damage to the device. Input voltage (common mode, safe) is the maximum voltage that can be applied to both input pins at the same time without damage to the device. The addition of the differential and common mode voltages shall not exceed ±36 volts and can be applied when the device power is on or off without damage to the device.

5/ Guaranteed if not tested to the limits specified.

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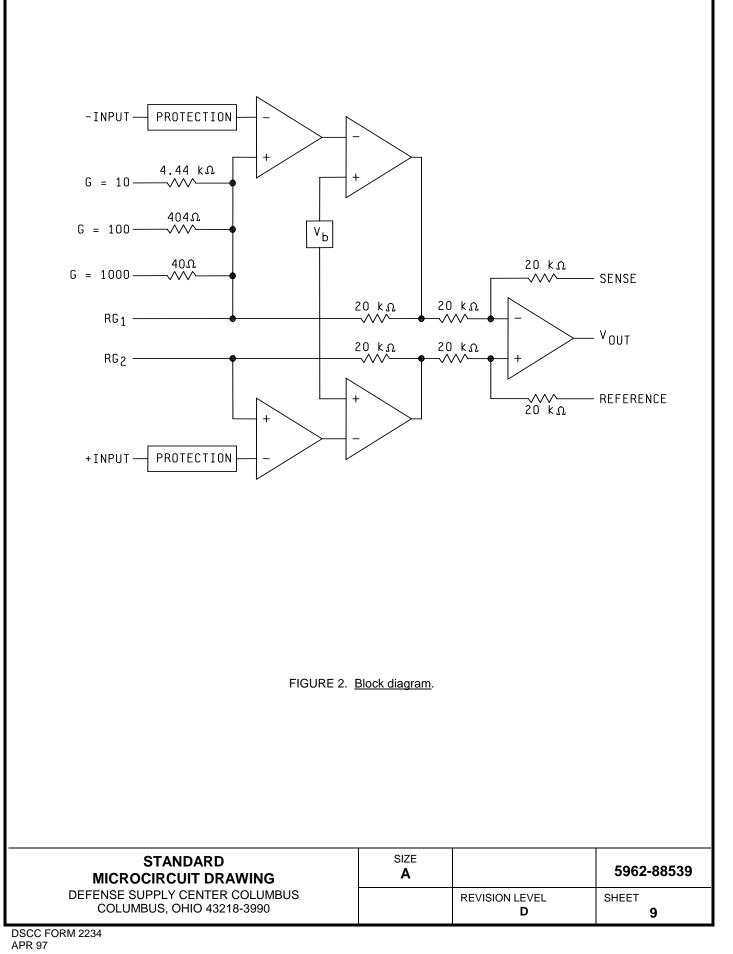
Device type	0	1
Case outline	E	2
Terminal number	Termina	l symbol
1 2 3 4 5 6 7 8 9 10 11 12 13 14 15 16 17 18 19 20	-INPUT +INPUT RG ₂ INPUT NULL INPUT NULL REFERENCE -Vs +Vs V _{OUT} SENSE G = 1000 G = 100 G = 10 OUTPUT NULL RG ₁ 	$\label{eq:states} \begin{array}{c} NC \\ -INPUT \\ RG_2 \\ INPUT \\ NULL \\ NC \\ INPUT \\ NULL \\ REFERENCE \\ -V_S \\ +V_S \\ NC \\ V_{OUT} \\ SENSE \\ G = 1000 \\ G = 100 \\ NC \\ G = 10 \\ OUTPUT \\ NULL \\ OUTPUT \\ NULL \\ RG_1 \end{array}$

NOTES:

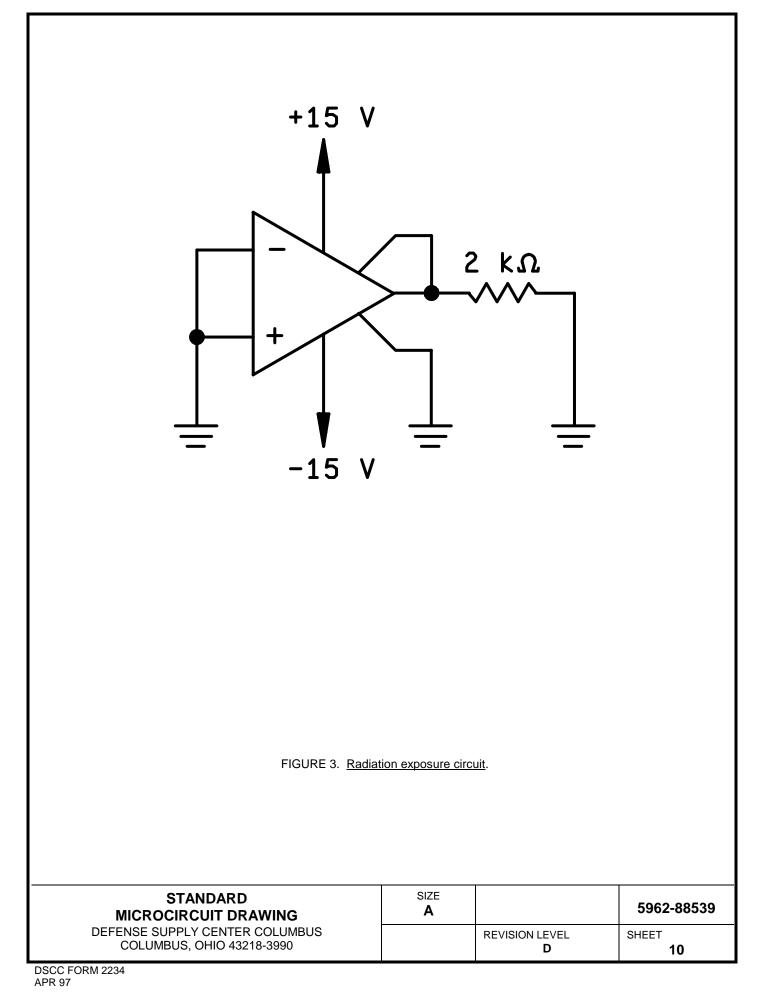
- 1. Case outline E, pins 11, 12, and 13; short to RG_2 for desired gain. 2. Case outline 2, pins 14, 15, and 17; short to RG for desired gain.

FIGURE 1. Terminal connections.

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3.6 <u>Certificate of compliance</u>. For device classes Q and V, a certificate of compliance shall be required from a QML-38535 listed manufacturer in order to supply to the requirements of this drawing (see 6.6.1 herein). For device class M, a certificate of compliance shall be required from a manufacturer in order to be listed as an approved source of supply in MIL-HDBK-103 (see 6.6.2 herein). The certificate of compliance submitted to DSCC-VA prior to listing as an approved source of supply for this drawing shall affirm that the manufacturer's product meets, for device classes Q and V, the requirements of MIL-PRF-38535 and herein or for device class M, the requirements of MIL-PRF-38535, appendix A and herein.

3.7 <u>Certificate of conformance</u>. A certificate of conformance as required for device classes Q and V in MIL-PRF-38535 or for device class M in MIL-PRF-38535, appendix A shall be provided with each lot of microcircuits delivered to this drawing.

3.8 <u>Notification of change for device class M</u>. For device class M, notification to DSCC-VA of change of product (see 6.2 herein) involving devices acquired to this drawing is required for any change that affects this drawing.

3.9 <u>Verification and review for device class M</u>. For device class M, DSCC, DSCC's agent, and the acquiring activity retain the option to review the manufacturer's facility and applicable required documentation. Offshore documentation shall be made available onshore at the option of the reviewer.

3.10 <u>Microcircuit group assignment for device class M</u>. Device class M devices covered by this drawing shall be in microcircuit group number 49 (see MIL-PRF-38535, appendix A).

4. VERIFICATION

4.1 <u>Sampling and inspection</u>. For device classes Q and V, sampling and inspection procedures shall be in accordance with MIL-PRF-38535 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein. For device class M, sampling and inspection procedures shall be in accordance with MIL-PRF-38535, appendix A.

4.2 <u>Screening</u>. For device classes Q and V, screening shall be in accordance with MIL-PRF-38535, and shall be conducted on all devices prior to qualification and technology conformance inspection. For device class M, screening shall be in accordance with method 5004 of MIL-STD-883, and shall be conducted on all devices prior to quality conformance inspection.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}C$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.
- 4.2.2 Additional criteria for device classes Q and V.
 - a. The burn-in test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The burn-in test circuit shall be maintained under document revision level control of the device manufacturer's Technology Review Board (TRB) in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.
 - b. Interim and final electrical test parameters shall be as specified in table IIA herein.
 - c. Additional screening for device class V beyond the requirements of device class Q shall be as specified in MIL-PRF-38535, appendix B.

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Test requirements	Subgroups (in accordance with MIL-STD-883, method 5005, table I)	Subgroups (in accordance v MIL-PRF-38535	
	Device class M	Device class Q	Device class V
Interim electrical parameters (see 4.2)	1	1	1
Final electrical parameters (see 4.2)	1, 2, 3 <u>1</u> /	1, 2, 3 <u>1</u> /	1, 2, 3 <u>1</u> / <u>2</u> /
Group A test requirements (see 4.4)	1, 2, 3	1, 2, 3	1, 2, 3
Group C end-point electrical parameters (see 4.4)	1	1	1 <u>2</u> /
Group D end-point electrical parameters (see 4.4)	1	1	1
Group E end-point electrical parameters (see 4.4)			1

TABLE IIA. Electrical test requirements.

<u>1</u>/ PDA applies to subgroup 1.

 $\frac{2}{}$ Delta limits as specified in table IIB shall be required where specified and the delta limits shall be computed with reference to the previous interim electrical parameters.

TABLE IIB. 240 hour burn-in and Group C end-point electrical parameters.

Parameter	Limit		imeter Limit Delta		lta
	Min	Max	Min	Max	
Voso		±3 mV		±3 mV	

4.3 <u>Qualification inspection for device classes Q and V</u>. Qualification inspection for device classes Q and V shall be in accordance with MIL-PRF-38535. Inspections to be performed shall be those specified in MIL-PRF-38535 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4 <u>Conformance inspection</u>. Technology conformance inspection for classes Q and V shall be in accordance with MIL-PRF-38535 including groups A, B, C, D, and E inspections and as specified herein except where option 2 of MIL-PRF-38535 permits alternate in-line control testing. Quality conformance inspection for device class M shall be in accordance with MIL-PRF-38535, appendix A and as specified herein. Inspections to be performed for device class M shall be those specified in method 5005 of MIL-STD-883 and herein for groups A, B, C, D, and E inspections (see 4.4.1 through 4.4.4).

4.4.1 Group A inspection.

- a. Tests shall be as specified in table IIA herein.
- b. Subgroups 4, 5, 6, 7, 8, 9, 10, and 11 in table I, method 5005 of MIL-STD-883 shall be omitted.

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4.4.2 Group C inspection. The group C inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.2.1 Additional criteria for device class M. Steady-state life test conditions, method 1005 of MIL-STD-883:

- a. Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to the preparing or acquiring activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
- b. $T_A = +125^{\circ}C$, minimum.
- c. Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.4.2.2 Additional criteria for device classes Q and V. The steady-state life test duration, test condition and test temperature, or approved alternatives shall be as specified in the device manufacturer's QM plan in accordance with MIL-PRF-38535. The test circuit shall be maintained under document revision level control by the device manufacturer's TRB in accordance with MIL-PRF-38535 and shall be made available to the acquiring or preparing activity upon request. The test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.

4.4.3 Group D inspection. The group D inspection end-point electrical parameters shall be as specified in table IIA herein.

4.4.4 <u>Group E inspection</u>. Group E inspection is required only for parts intended to be marked as radiation hardness assured (see 3.5 herein). RHA levels for device classes M, Q, and V shall be as specified in MIL-PRF-38535. End-point electrical parameters shall be as specified in table IIA herein.

4.4.4.1 <u>Total dose irradiation testing</u>. Total dose irradiation testing shall be performed in accordance with MIL-STD-883 method 1019 condition A and as specified herein.

4.4.4.1.1 <u>Accelerated aging test</u>. Accelerated aging tests shall be performed on all devices requiring a RHA level greater than 5k rads(Si). The post-anneal end-point electrical parameter limits shall be as specified in table I herein and shall be the pre-irradiation end-point electrical parameter limit at 25° C. Testing shall be performed at initial qualification and after any design or process changes which may affect the RHA response of the device.

4.4.4.2 <u>Dose rate burnout</u>. When required by the customer, test shall be performed on devices, SEC, or approved test structures at technology qualifications and after any design or process changes which may effect the RHA capability of the process. Dose rate burnout shall be performed in accordance with test method 1023 of MIL-STD-883 and as specified herein.

5. PACKAGING

5.1 <u>Packaging requirements</u>. The requirements for packaging shall be in accordance with MIL-PRF-38535 for device classes Q and V or MIL-PRF-38535, appendix A for device class M.

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6. NOTES

6.1 <u>Intended use</u>. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.1.1 <u>Replaceability</u>. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.2 <u>Configuration control of SMD's</u>. All proposed changes to existing SMD's will be coordinated with the users of record for the individual documents. This coordination will be accomplished using DD Form 1692, Engineering Change Proposal.

6.3 <u>Record of users</u>. Military and industrial users should inform Defense Supply Center Columbus (DSCC) when a system application requires configuration control and which SMD's are applicable to that system. DSCC will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DSCC-VA, telephone (614) 692-0544.

6.4 <u>Comments</u>. Comments on this drawing should be directed to DSCC-VA , Columbus, Ohio 43218-3990, or telephone (614) 692-0547.

6.5 <u>Abbreviations, symbols, and definitions</u>. The abbreviations, symbols, and definitions used herein are defined in MIL-PRF-38535 and MIL-HDBK-1331.

6.6 Sources of supply.

6.6.1 <u>Sources of supply for device classes Q and V</u>. Sources of supply for device classes Q and V are listed in QML-38535. The vendors listed in QML-38535 have submitted a certificate of compliance (see 3.6 herein) to DSCC-VA and have agreed to this drawing.

6.6.2 <u>Approved sources of supply for device class M</u>. Approved sources of supply for class M are listed in MIL-HDBK-103. The vendors listed in MIL-HDBK-103 have agreed to this drawing and a certificate of compliance (see 3.6 herein) has been submitted to and accepted by DSCC-VA.

STANDARD MICROCIRCUIT DRAWING	SIZE A		5962-88539
DEFENSE SUPPLY CENTER COLUMBUS COLUMBUS, OHIO 43218-3990		REVISION LEVEL D	SHEET 14

STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 04-08-06

Approved sources of supply for SMD 5962-88539 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38535 during the next revision. MIL-HDBK-103 and QML-38535 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DSCC-VA. This information bulletin is superseded by the next dated revision of MIL-HDBK-103 and QML-38535.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /	Replacement military specification part number
5962-8853901EA	24355 (2)	AD524SD/883B	M38510/14301BEX
5962-88539012A	<u>3/</u>	AD524SE/883B	
5962-8853901VEA	24355 (5)	AD524SD/QMLV	
5962R8853901VEA	24355 (5)	AD524SD/QMLR	

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the vendor to determine its availability.
- <u>2</u>/ <u>Caution</u>. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.
- <u>3/</u> Not available from an approved source of supply.

Vendor CAGE number	Vendor name and address
24355	Analog Devices (2) RT 1 Industrial Park PO Box 9106 Norwood, MA 02062 Point of contact: 804 Woburn Street Wilmington, MA 01887-3462
24355	Analog Devices (5) RT 1 Industrial Park PO Box 9106 Norwood, MA 02062 Point of contact: 1500 Space Park Drive PO Box 58020

Santa Clara, CA 95052-8020

The information contained herein is disseminated for convenience only and the Government assumes no liability whatsoever for any inaccuracies in the information bulletin.